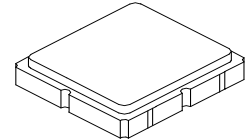




- *Hermetically sealed Surface Mount package*
- *Complies with Directive 2002/95/EC (RoHS)*

**Absolute Maximum Ratings**

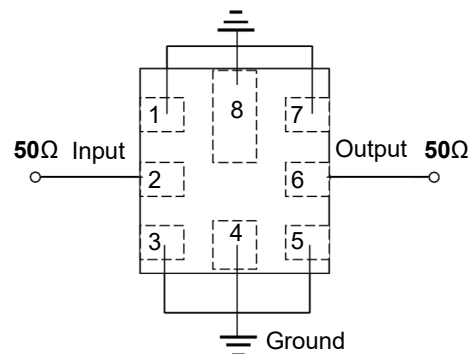
Rating	Value	Units
Maximum Input Power	10	dBm
DC Voltage	10	VDC
Operating Temperature	-40 to +85	°C
Storage Temperature	-40 to +85	°C

SF2424D**505 MHz
SAW Filter****SM3838-8 Case****Electrical Characteristics**

Characteristic		Sym	Notes	Minimum	Typical	Maximum	Units
Center Frequency		f _C			505		MHz
Insertion Loss	500 - 508 MHz	IL			2.6	4.1	dB
	500 - 510 MHz				2.8	4.1	
Amplitude Ripple	500 - 508 MHz				0.5	2.5	dB
	500 - 510 MHz				0.6	2.5	
Attenuation (Reference level from 0dB)							dB
404 to 463.2 MHz				42	50		
544 to 604 MHz				42	48		
Temperature Coefficient of Frequency					-36		ppm/k
Terminating Source Impedance (single) Z _S				50			Ω
Terminating Load Impedance (single) Z _L							
Footprint Size: 3.8 X 3.8				SM3838-8			
Lid Symbolization (Y=Year, WW=week, S=shift)		B38//YWWS					

Electrical Connections

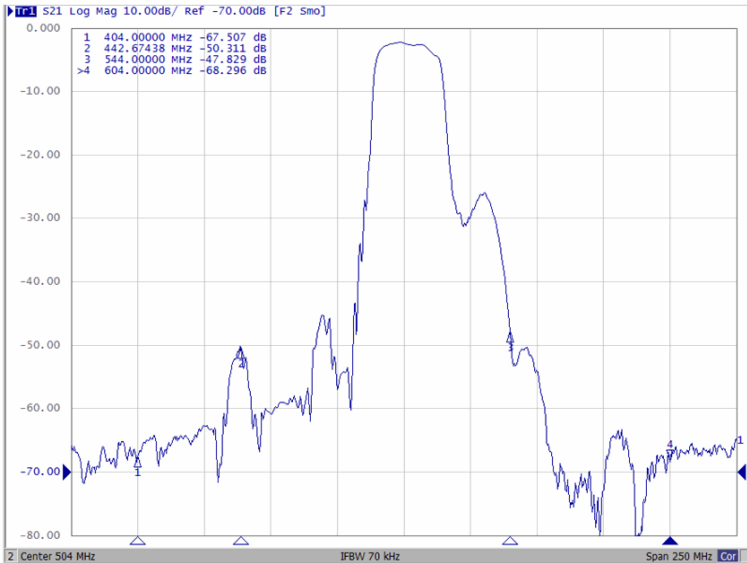
Connection	Terminals
Input	2
Output	6
Ground	All Others

**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.****NOTES:**

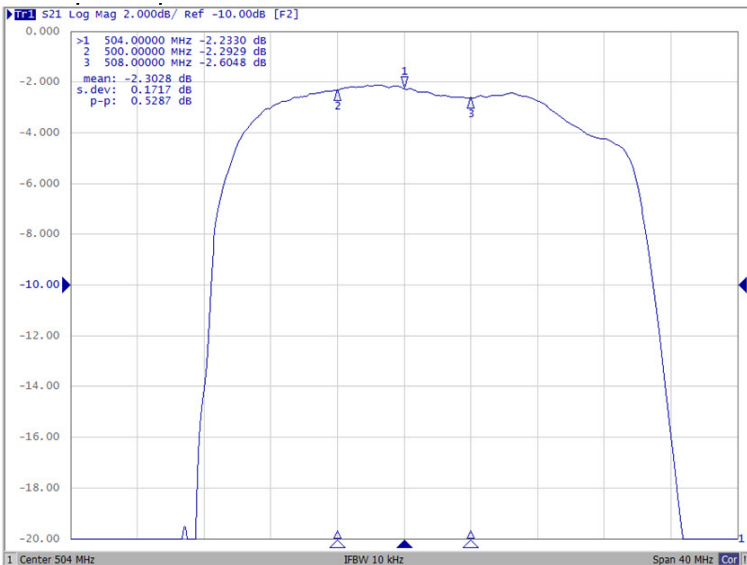
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

Frequency Characteristics

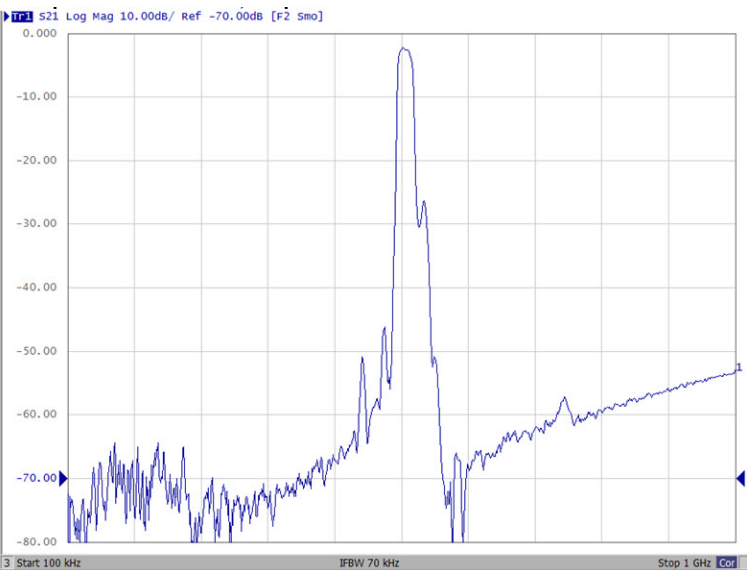
S21 Response: Center 504 MHz, Span 250 MHz



S21 Response: Span 40 MHz



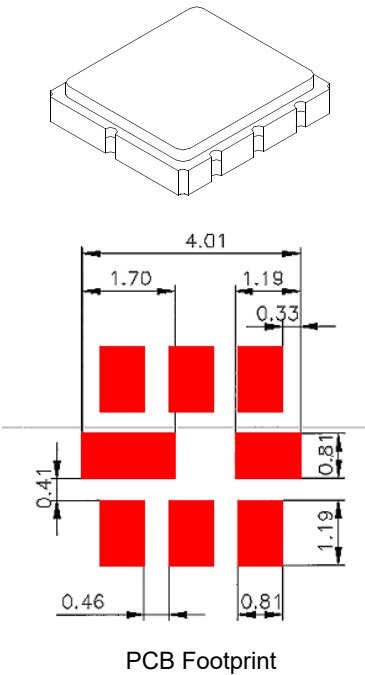
S21 Response: 0 - 1000 MHz



SM3838-8 Case

8-Terminal Ceramic Surface-Mount Case

3.8 X 3.8 mm Nominal Footprint

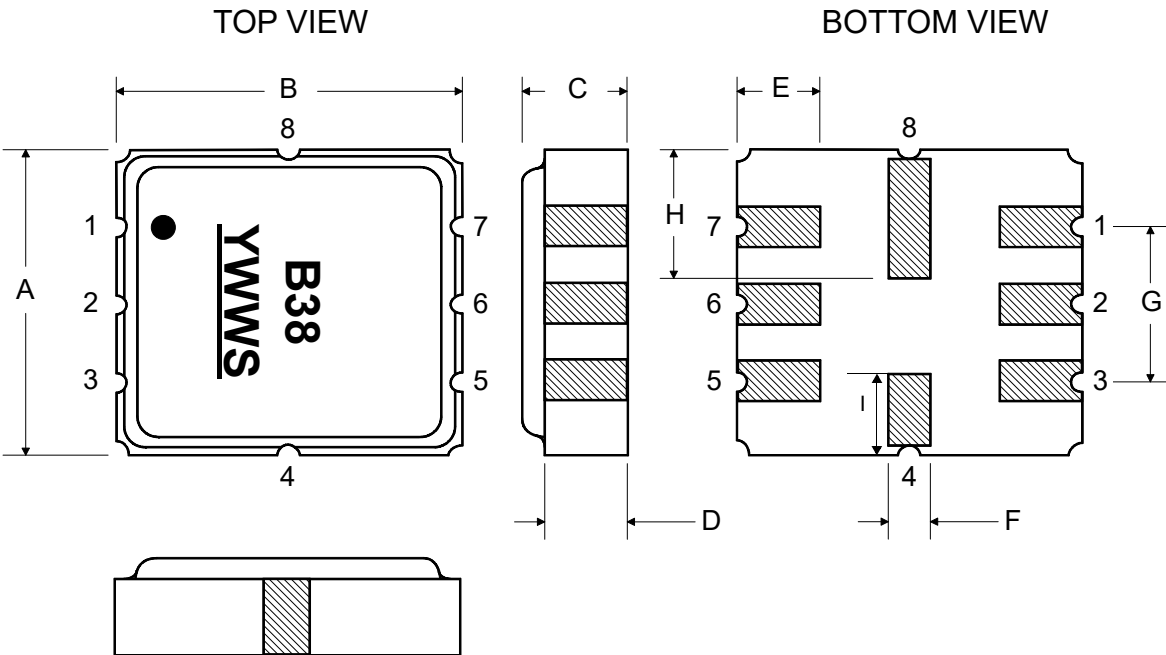


Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.65	3.80	3.95	0.143	0.149	0.155
B	3.65	3.80	3.95	0.143	0.149	0.155
C	-	-	1.40	-	-	0.055
D	0.95	1.10	1.25	0.037	0.043	0.049
E	0.90	1.00	1.10	0.035	0.040	0.043
F	0.50	0.60	0.70	0.020	0.024	0.028
G	2.39	2.54	2.69	0.090	0.100	0.110
H	1.40	1.75	2.05	0.055	0.069	0.080
I	0.90	1.00	1.10	0.035	0.040	0.043

Electrical Connections		
	Connection	Terminals
Port 1	Input	2
Port 2	Output	6
	Ground	All Others

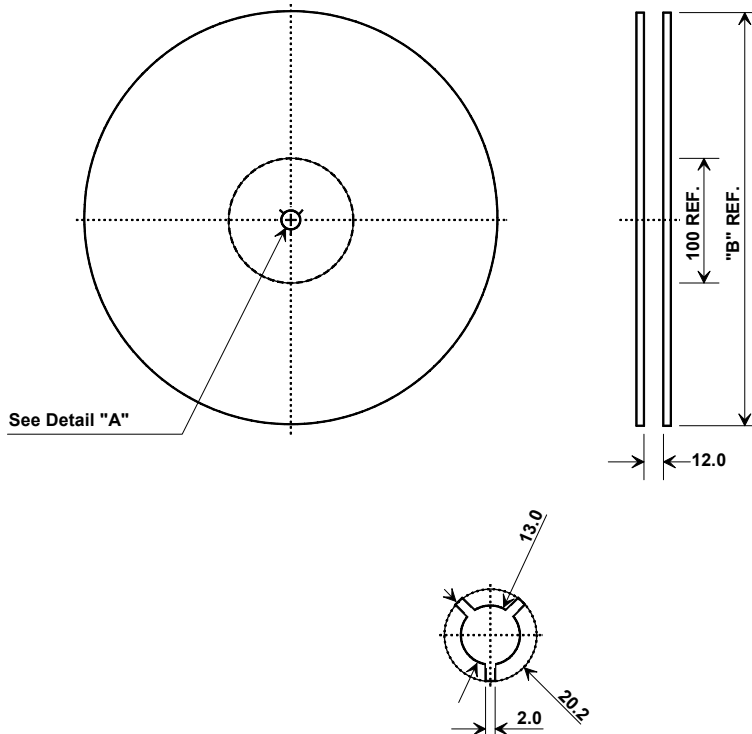
Dot Indicates Pin 1

Materials	
Solder Pad Termination	Au plating 30 - 60 μInches (76.2-152 μM) over 80-200 μInches (203-508 μM) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 μInches Thick
Body	Al ₂ O ₃ Ceramic
Pb Free	



Tape and Reel Specifications

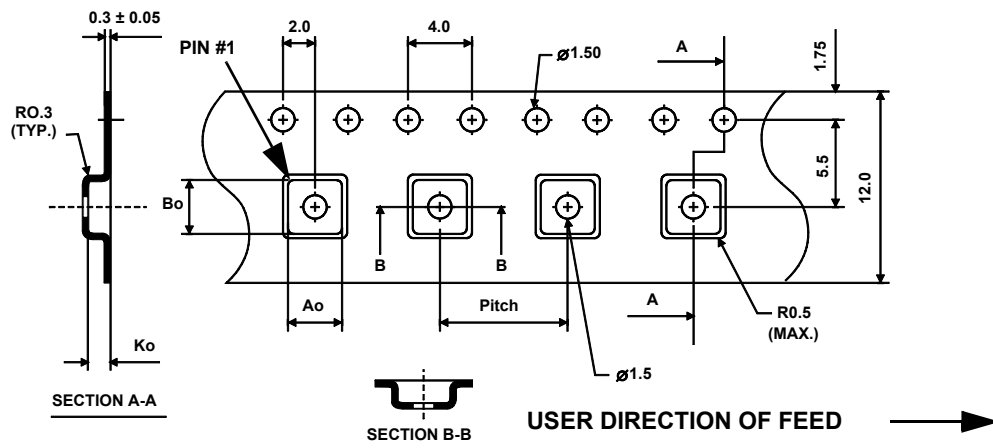
Tape and Reel Standard per ANSI/EIA-481



“B” Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

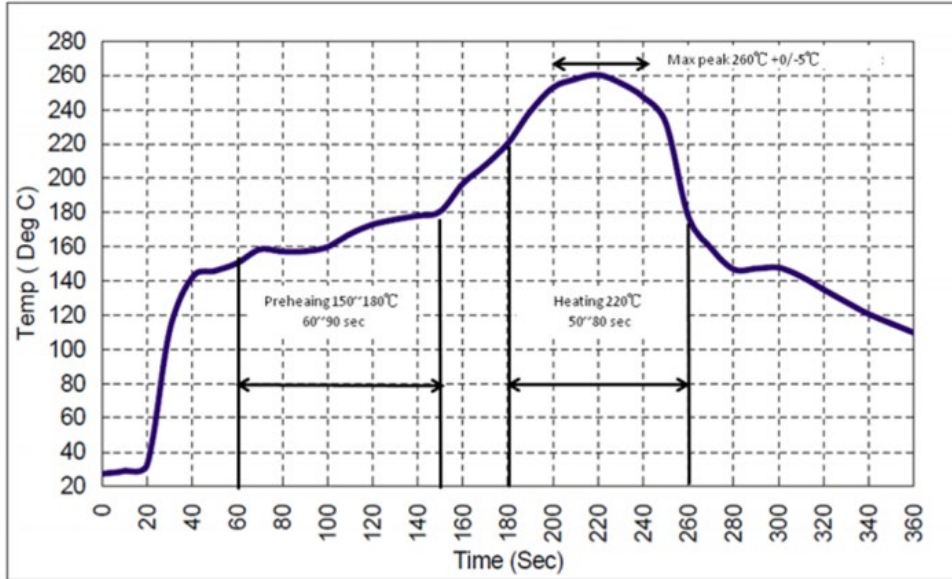
COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	4.25 mm
Bo	4.25 mm
Ko	1.30 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.



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